Supplementary Information

Robust Ag Nanoplate Ink for Flexible Electronics Packaging

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Fig. S1 (a) Diameter and (b) thickness distributions of the silver nanoplate paste, (c) length and (d) diameter distributions of the silver nanowire paste.



Fig. S2 (a) Schematic illustration of wire configuration during bonding, and image of bonded copper wires using (b) Ag nanoplate paste and (c) Ag nanowire paste.



Fig. S3 HRTEM images of a Ag nanoplate edge.



Fig. S4 FTIR spectra of Ag nanoplates post- annealed at room temperature, 160 $^\circ C$ and 250 $^\circ C.$



Fig. S5 (a) Top view and (b) cross-sectional view of sintered silver nanowire paste.



Fig. S6 Thermal analysis of the Ag nanoplates and PVP in air and N_2 atmosphere.



Fig. S7 (a) TEM image of organic nanowire, (b) Energy dispersive X-ray spectroscopy (EDS) image of the organic nanowire.